EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	557	"257"/\$.ccls. and ((semiconductor adj (device or structure)) and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/22 08:12
L3	1494	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 08:13
L7	1043	(438/459).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 08:15
L8	1154	(438/113).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 08:26
L9	3687	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 08:54
L10	972	(438/458).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 09:20

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S1	1	09/594510	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:27
S2	118011	substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:29
S3	8058	substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:31
S4	2481	substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:36
S5	393	"438"/\$.ccls. and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:32
S6	1032	"257"/\$.ccls. and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:32

EAST Search History

S7	85	"438"/15,110,113,114.ccls. and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:33
S8	0	((semiconductor adj (device or structure)) and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616").clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:37
S9	948	((semiconductor adj (device or structure)) and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 12:38
S11	237	"438"/\$.ccls. and ((semiconductor adj (device or structure)) and substrate and (pad or (conductive adj trace)) and (die or chip or (semiconductor adj (device or structure or element))) and (bond\$3 or attach\$4) and (input and output) and test\$4 and (cutting or cut or dic\$3 or singulat\$4) and @ad<="20000616")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/21 14:55